

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: KIRA, et al.

Serial No.: 09/548,313

Filed: April 12, 2000

Group Art Unit: 2652

Examiner: Craig A. Renner

PTO Confirmation: 6169

FOR: HEAD ASSEMBLY HAVING INTEGRATED CIRCUIT CHIP COVERED BY  
LAYER WHICH PREVENTS FOREIGN PARTICLE GENERATION  
(As Amended)

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JUL 30 2002

Technology Center 2600

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents  
Washington, D.C. 20231

July 25, 2002

Sir:

In response to the Office Action dated **March 28, 2002**, please amend the above-identified application as follows:

IN THE TITLE:

Please amend the title of the invention, in its entirety, so as to read as follows:

-- HEAD ASSEMBLY HAVING INTEGRATED CIRCUIT CHIP COVERED BY LAYER  
WHICH PREVENTS FOREIGN PARTICLE GENERATION--

IN THE CLAIMS:

Please cancel claim 7 without prejudice.

Please amend claims 1 and 8 as follows:

1. (Amended) A head assembly comprising: